

### EDGE HANDLING WAFER PREALIGNER

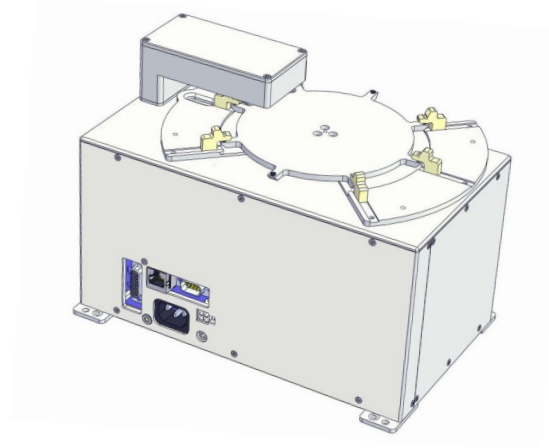
## LPA6EH-3

**Innovative, high-performance, all-in-one design** eliminates external controller and interconnecting cables while maintaining drop-in compatibility

Driven by ultra low inertia brushless motors for **smooth, instant response**

Advanced scanning electronics capable of detecting **transparent, semi-transparent and opaque objects** without mechanical repositioning between different wafer sizes

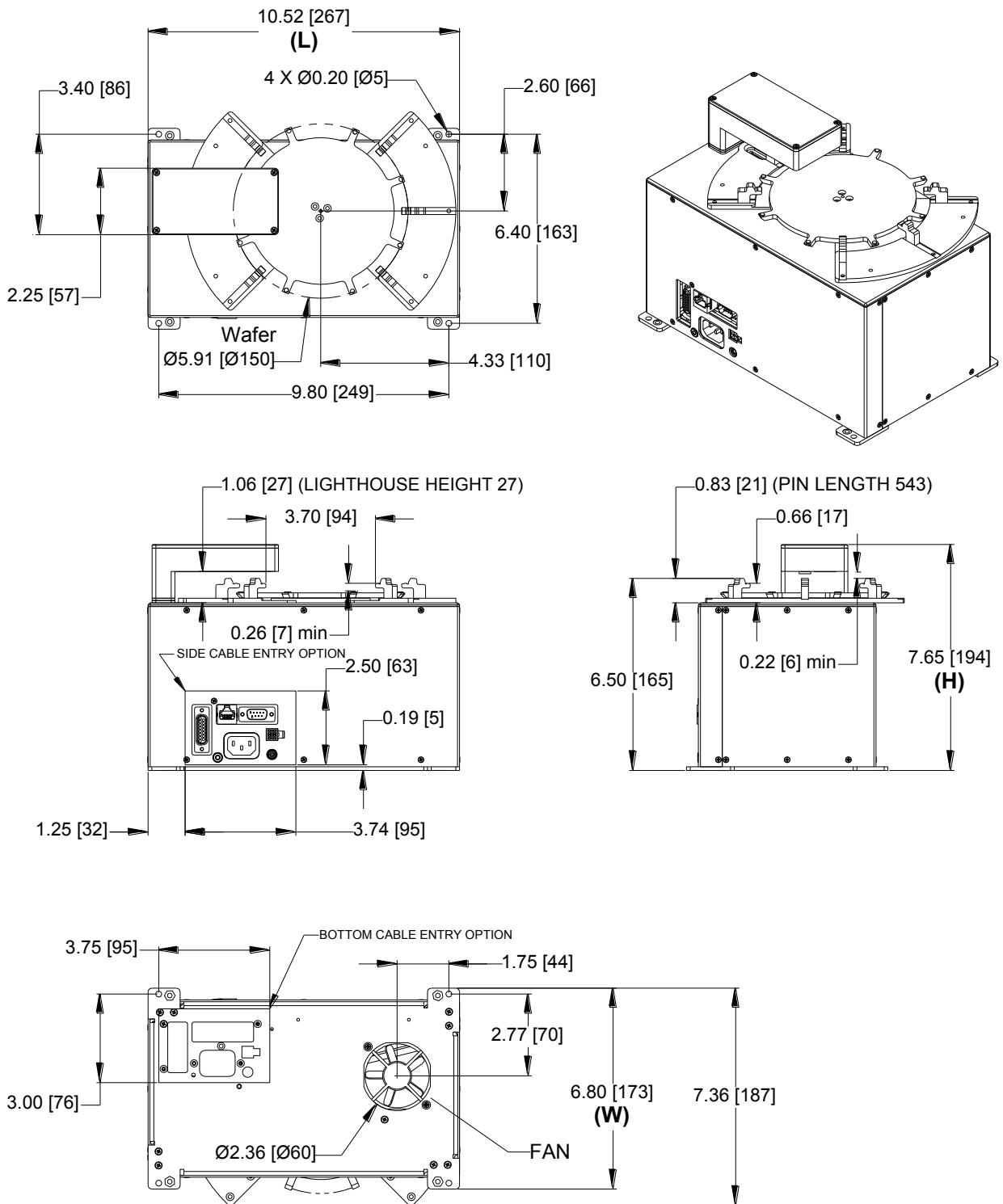
Motion control software featuring a comprehensive set of commonly used commands enabling **compatibility and interface with a variety of semiconductor platforms**



### LPA6EH-3 SPECIFICATIONS

<b>Wafer Diameter</b>		150mm
<b>Wafer Opacity</b>		Transparent, Semi-Transparent, Opaque
<b>Square Substrates</b>		Not Applicable
<b>Wafer Handling</b>		Edge Handling
<b>Centering Accuracy</b>		±25um on the Prealigner Chuck
<b>Angular Accuracy (3 Sigma)</b>	<b>10000 CPR Encoder</b>	±0.04° on the Prealigner Chuck
	<b>24000 CPR Encoder</b>	±0.02° on the Prealigner Chuck
<b>Servo Axes</b>		Three
<b>Host Communication</b>		RS232, Ethernet
<b>Max Initial Wafer Offset</b>		2mm
<b>Body Dimensions (W x L x H)</b>		173mm x 267mm x 194mm
<b>Footprint Compatibility</b>		LPA4EH-3, LPA5EH-3, LPA8EH-3 LPA26-3, LPA38-3, LPA58-3
<b>Weight</b>		5.60kg
<b>Facilities Required</b>		100-240VAC, 50/60Hz, 48VA, or 24VDC/2A
<b>Flat/Notch Compatibility</b>		SEMI Standards Compliant
<b>Cleanliness</b>		Class 1
<b>MTBF</b>		More than 70000 hours

### LPA6EH-3 GENERAL DIMENSIONS



NOTE: All Dimensions — inch [mm]

For model numbers and options download: [LPA Series Prealigners Ordering Guide.pdf](#)